TEC Specifications

CP-12701(30,30)

Products Introduction

- The Ceramic Plate(CP)Series of Thermoelectric Modules(TEMs) is considered "the standard" in the thermoelectric industry.
- Provide high performance and high reliability cooling modules for the field of consumer and the field of industrial equipment.
- Provide nearly 200 kinds of models, with different cooling capacity,geometric shapes.
- Provide Rohs standard products for long term use at 80℃ as well as special solder product for maximum use temperature at 150℃.
- Provide a fine flatness(±0.03mm) and coarse grind (±0.08mm) for selection.
- Provide high flexibility of silicone (RTV) and high waterproofness epoxy glue (Epoxy) sealed for selection.

Features

- Using 99.99% purity metal.
- Reliable Solid State Operation
- Precise temperature control
- Lapping with0.025mm tolerance
- ΔTmax is 66℃ to 70℃
- Provide customized services

Applications

- Food & Beverage Cooling
- Daily Beauty Equipment
- Portable cooler box
- Chillers (Liquid Cooling)
- Cold and hot air system
- Battery storage cabinet

Performance Specifications

Hot plate temperature Th=	**23**	℃	**50**	℃
Qcmax	14.47	W	15.49	W
Maximum temperature difference (dTmax)	67.00	℃	72.00	℃
Maximum input current (Vmax)	1.70	A	1.70	A
Maximum input voltage （Imax）	15.37	V	15.37	V
Module Resistance	7.40	Ohms	8.50	Ohms
Resistance Tolerance	9%			

Sealing Option

Code	Sealant	Color	Temperature range	Description
NS	Not sealant			
RTV	**RTV**	White	**-60 to 200℃**	**Non-corrosive, silicone adhesive sealant**
EP	Eposy	Black	-50 to 120℃	Low-density synthetic foam epoxy sealant
CS	Customized			Meet customer requirements

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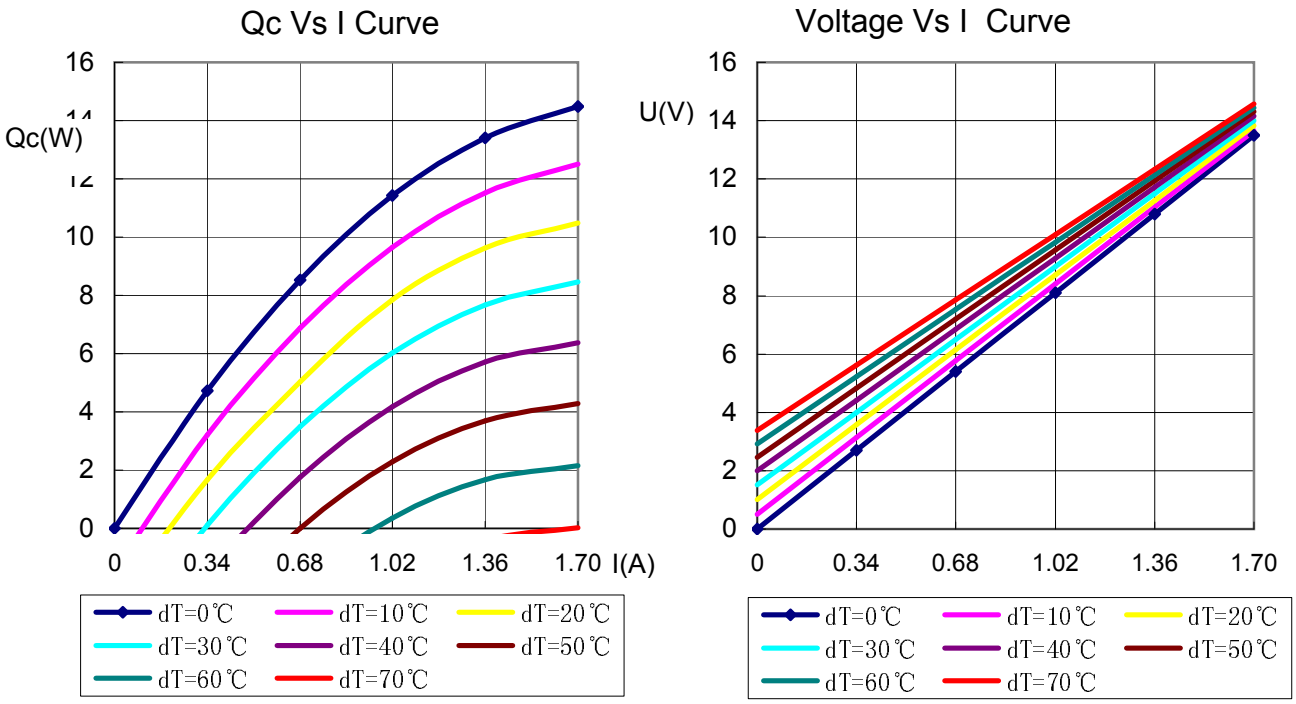
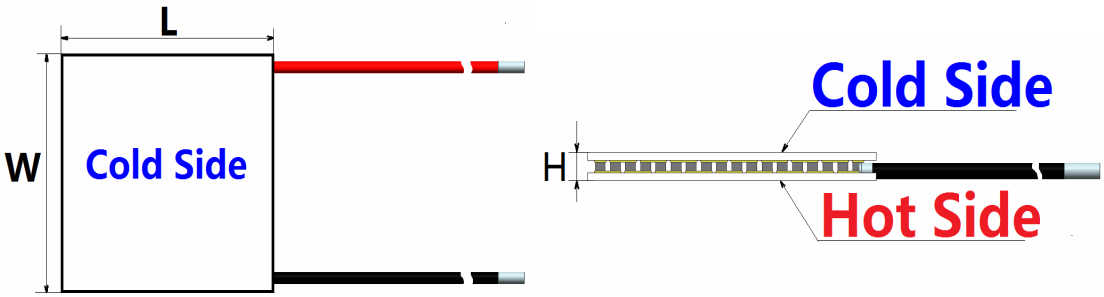
Performance Curves



Geometric Characteristics



W(mm)	L(mm)	H(mm)	Flatness(mm)	Wire length(mm)	Wire type	Note
30	30	30	4.98	150	22#	/

OperationTips

Voltage / current should be less than the maximum voltage / current；

Use Direct current power only；

Stored and operated below 120 ℃；